

**PRODUCT DESCRIPTION:**

AA-BOND G298 is a two component, gold-filled, electrically and thermally conductive epoxy designed for hybrid microelectronic and semiconductor packaging.

**GENERAL PROPERTIES:**

<b>Components</b>	A & B
<b>Appearance</b>	Resin: Brown, Hardener: Dark Brown
<b>Cure Type</b>	Room temperature or Heat cure
<b>Benefits</b>	<ul style="list-style-type: none"> <li>Gold filled epoxy allows for anti-oxidation of contacts and terminals in high reliability devices.</li> <li>It can be used in medical circuits using traditional hybrid packaging technologies.</li> <li>High viscosity paste allows for precision deposition onto circuits by means of printing and delicate hand processes.</li> </ul>
<b>Mix Ratio by weight</b>	100:4 / Resin: Hardener
<b>Substrates</b>	Metals, ceramics, glass, glass fabrics, wood leather and rigid plastics
<b>Operating Temperature</b>	Continuous: - 55°C to 275°C Intermittent: - 55°C to 375°C
<b>Typical Applications</b>	<ul style="list-style-type: none"> <li>Adhesive for joining die and SMDs onto the hybrid circuits.</li> <li>Repairing defective Au thick-film conductor traces and contact pads.</li> <li>Resisting oxidation and electro-migration in high-reliability micro-electronics.</li> <li>Joining material as alternative to high temperature Au-Sn eutectic solders processes exceeding 300°C.</li> </ul>

**UNCURED PROPERTIES:**

<b>Viscosity</b> (@ 0.5 RPM/23°C):	> 400,000 cPs
<b>Pot Life</b>	30 min
<b>Thixotropic Index</b>	NA
<b>Degradation Temp. (TGA):</b>	483°C
<b>Particle Size:</b>	≤ 50 Microns

**MISC PROPERTIES:**

<b>Volume Resistivity</b>	@ 23°C: ≤ 0.0009 Ohm-cm
<b>Glass Transition Temp, Tg</b>	≥ 100°C (Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)
<b>Die Shear Strength</b>	@ 23°C: ≥ 5 Kg / 1,700 psi
<b>Shelf life</b>	1 year

**CURE SCHEDULE:**

<b>15 min</b>	@ 120°C
<b>90 min</b>	@ 80°C
<b>10 Hours</b>	@ 50°C
<b>24 hours</b>	@ 25°C

**GENERAL INFORMATION:**

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

**HOW TO USE:**

- Carefully clean and dry all surfaces to be bonded
- Apply this completely mixed adhesive to the prepared surfaces, and gently press these surfaces together. Contact pressure is adequate for strong, reliable bonds; however, maintain contact until adhesive is completely cured
- Some separation of components is common during shipping and storage. For this reason, it is recommended that the contents of the shipping container be thoroughly mixed prior to use
- Some ingredients in this formulation provided may crystallize when subjected to low temperature storage. A gentle warming cycle of 52°C for 30 minutes prior to mixing components may be necessary. Crystallized epoxy components do not react as well as liquid components and should be re-dissolved prior to use for best results

**AVAILABILITY:**

This epoxy can be supplied in many different packages.

**Atom Adhesives**

Email: [info@atomadhesives.com](mailto:info@atomadhesives.com)

200 Allens Ave, Providence, RI 02903

Phone: (888) 522-6742 - Fax: (877) 522-6742